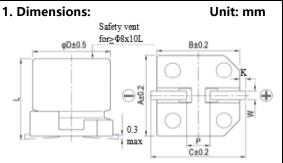


#### Specification: CAE227M1CHUTEG7TR6

#### **CDUT Series**



φD	L	A	В	C	P	K	W
4	5.4 -0.3/+0.5	4.3	4.3	5.1	1.0	0.5max	0.5~0.8
5	5.4 -0.3/+0.5	5.3	5.3	6.0	1.5	0.5max	0.5~0.8
6.3	5.4 -0.3/+0.5	6.6	6.6	7.2	2.1	0.5max	0.5~0.8
6.3	7.7 -0.3/+0.5	6.6	6.6	7.2	2.1	0.5max	0.5~0.8
8	6.5 -0.3/+0.5	8.3	8.3	9.1	3.1	0.5max	0.8~1.1
8	10.2±0.5 or 10.5±0.5	8.3	8.3	9.1	3.1	0.5max	0.7~1.2
10	10.2±0.5 or 10.5±0.5	10.3	10.3	11.1	4.5	0.5max	0.7~1.3

### 2.Technical Parameter:

Aillen	Cap.	Cap.	Rate	Surge	Oper.	Case Size	Leakage	Disspation	ESR Max	ESR Max	R.C Max	R.C Max	Load
P/N	(μF) at +20°C	Tol.(%) at +20°C	Volt.	Volt . (VDC)	Temp.	D*L (mm)	Current <sup>1)</sup> Max at +20°C(μA)	Factor Max at +20°C 120Hz(%)	at +20°C 120Hz (Ω)	_	at 105°C 120Hz (mA rms)	at 105°C 100KHz (mA rms)	Life at 105°C ( hours )
CAE227M1CHUTEG7TR6	220	±20%	16	18.4	-55~105	6.3x7.7	35.20	20	/	/	110	/	2000

Remark::

 $L.C. \leq 0.01CV \ or \ 3(\mu A) \ whichever \ is \ greater, After \ 2 \ minute \ measured \ with \ rated \ working \ voltage \ applied, C: \ Capacitance \ (\mu F) \ V: \ Rated \ DC \ Working \ Voltage \ (V).$ 

## 3. Multiplier For Ripple Current&Temperature coefficient

Remark: When capacitors are operated at temperatures other than +105°C, and frequency other than 100kHz, the maximum Ripple Current(R.C.) must be multiplied by the factors shown in below table.

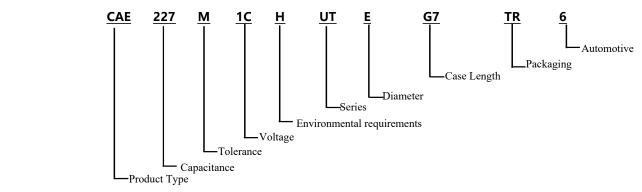
Frequency	50Hz	120Hz	300Hz	1kHz	≥10kHz
Coefficient	0.64	0.70	0.75	0.85	1.00

Temperature(°C)	105	85	≤70
Coefficient	1.0	1.5	2.0

#### 4. Characteristics

ltem	Characteristics												
	The capacitor is stored at a temperature of 105°C ±2 with rated voltage applied continuously for 2000+48/0 hours, Then the product should be tested after 16 hours recovering time at atmospheric conditions. The result should meet the following table:												
Load Life	Capacitance Chang	Within ±30% of initial value											
Load Life	Dissipation Factor			Not more than 200% of the specified value									
	Leakage Current	Not more than the specified value											
	The capacitors are then stored with no voltage applied at a temperature of $105\pm2^{\circ}$ for $1000+48/0$ hours. Following this period the capacitors shall be removed from the test chamber and be allowed to stabilized at room temperature for $4\sim8$ hours.Next they shall be connected to a series limiting resistor( $1k\pm100\Omega$ ) with D.C. rated voltage applied for 30min. After which the capacitors shall be discharged, and then, tested the characteristics.												
Shelf Life	Capacitance Chang	ge		Within ±30% of initial value									
	Dissipation Factor	Not more than 200% of the specified value											
	Leakage Current	Not more than 200% of the specified value											
	Rated Voltage (V)		6.3	10	16	25	35	50	63	100			
I avv Tamananatuma	Z-25°C/Z+20°C	<Ф8	4	3	2	2	2	2	2	2			
Low Temperature Stability	(120Hz)	≥Φ8	5	4	3	2	2	2	2	2			
otability .	Z-55°C/Z+20°C	<Ф8	12	8	4	4	3	3	3	3			
	(120Hz)	≥Φ8	8	8	6	4	3	3	3	3			

# 5. Part Number System:



Specification: CAE227M1CHUTEG7TR6 CDUT Series

# 6. Welding methods and applicability

#### 6.1 Methods the following:

Reflow soldering: please follow the temperature condition during welding. If high temperature is used, please measure and inform the capacitor temperature and reflow soldering condition. The product size is larger and its rising temperature is slower. It is not necessary to adjust the temperature of the reflow solder in accordance with the size of the product. For example, the products of 4 and 10 will be installed in the PCB over tin furnace.

#### 6.2 Precautions for soldering tin:

Related factors of reflow soldering temperature:

The product size is larger and its temperature rises slowly

Product installation position: The temperature of PCB center is lower than that of PCB<sub>o</sub>

#### 6.3 Reflow soldering:

If possible, avoid reflow soldering twice

If repeated reflux is unavoidable, measure and inform the first and second reflux temperature, and the time of reflow soldering

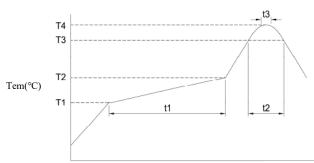
#### 6.4 Please do not 3 times of reflow soldering:

Please follow the following conditions when soldering tin soldering:

6.4.1 Soldering iron maximum temperature: 350±5°C

6.4.2 Welding time: 3+1/-0S

## Conditions for the use of lead-free reflow soldering .:



Time(S)

## Test method and peak temperature permissible range

	<u> </u>	<u>,                                      </u>							
Products	category	SMD aluminum electrolytic capacitor							
Rated vol	tage (V)	4~50		≥63	4~100		≥160		
Produ	ict size	4~6	4~6.3x5.4~7.7 8~		-18	≥12.5			
1	Tem $(T_1 \sim T_2, \ ^{\circ}C)$								
preheating	Time $(t_1)$ Max,S		100						
TT1 1 C.1	Tem $(T_3, ^{\circ}C)$	217	230	217	217	230	217		
The duration of the	Time $(t_2)$ Max,S	90	60	60	60	40	40		
The highest	Tem (T₄, °C)	20	260		250		240		
temperature	Time $(t_3)$ Max,S	5							
Return tl	he number	≦2							

#### Remark:

- 1)Please contact us if the conditions of use are higher than those listed above;
- 2)When performing second reflow soldering, please make sure the temperature of capacitor has cooled to 5 ~ 35 °C;
- 3)If the reflow condition is based on IPC/JEDEC(J-STD-020), please contact us;



#### 4)Reflow Soldering Considerations

Reflow soldering will reduce the rated electrostatic capacity of the product, and it should be confirmed whether reflow soldering condition meets the specification of recommended reflow soldering

Although the actual reflow condition change is still based on the reflow soldering method, please note that the highest temperature and the electrode terminal at the bottom of the aluminum shell must not exceed the maximum temperature

OP - CAP products during the process of reflow heating temperature should increase to more than 200 °C

If the reflow condition temperature or duration is greater than the above table, the OP-CAP product will be damaged. The electrostatic capacity of the product is reduced by about 50%, the leakage current is large (up to m A), and the outside of the capacitor is damaged

# 7.Recommended Land Size (Unit: mm)

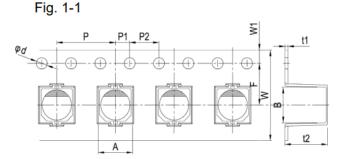
Size	X	Y	а	Pictorial Representation
Ф4	1.6	2.6	1	
Ф5	1.6	3	1.4	Y
Ф6.3	1.6	3.5	1.9	a a
Φ8	2.5	3.5	3	_ J Y
Ф10	2.5	4	4	<del>&lt; ×</del>

## **8.** Taping Specifications:

Applicable standard JIS C0806 and IEC 60286.

## 8.1Carrier Tape and Dimension

Size : $\emptyset 4 \sim \emptyset 10$ 



Size	W	P	F	A	В	$t_2$	Φd	$\mathbf{P}_{1}$	$P_2$	t <sub>1</sub>	$W_1$	Applicable	
Sie	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	1.0	14	- 2	•1	1	rippirodero	
Φ4*5.4	12	8	5.5	4.7	4.7	5.8	1.5	2.0	4.0	0.4	1.75	Fig.1-1	
Ф5*5.4	12	12	5.5	6.0	6.0	5.8	1.5	2.0	4.0	0.4	1.75		
Ф6.3*5.4	16	12	7.5	7.0	7.0	5.8	1.5	2.0	4.0	0.4	1.75		
Ф6.3*7.7	16	12	7.5	7.0	7.0	8.3	1.5	2.0	4.0	0.4	1.75	E: - 1 2	
Φ8*6.5	16	12	7.5	8.7	8.7	6.8	1.5	2.0	4.0	0.4	1.75	Fig.1-2	
Φ8*10.2/10.5	24	16	11.5	8.7	8.7	11	1.5	2.0	4.0	0.4	1.75		
Ф10*10.2/10.5	24	16	11.5	10.7	10.7	11	1.5	2.0	4.0	0.4	1.75		

Fig. 1-2